

ANP 系列 ANP-1 支持无加压连接, 并可用于 Ni, Cu 的连接。

Properties	ANP-1	ANP-8	Remarks
Viscosity	50~300Pa·s	50~300Pa·s	可调
Sintering Temperature	250°C ↑ x300sec	300°C ↑ x300sec	会因设备和样品的状态而变化
Sintering Pressure	10MPa ↑	20MPa ↑	
Thermal conductivity (W/m·K)	330W/m·K	350W/m·K	
Shear Strength	40MPa	40MPa	
Target Metal	Ag,Au,Cu,Ni,Pd,Pt	Ag,Au,Cu,Ni,Pd,Pt	

ASTRO 系列

预干燥后可实现预固定

ASTRO-HP	
Viscosity	10~100Pa·s
Sintering Temperature	250°C ↑ x300sec
Sintering Pressure	10MPa ↑
Thermal Conductivity (W/m·K)	330W/m·K
Shear Strength	30MPa
Target Metal	Ag,Au,Cu,Pd,Pt

实现低温连接

ASTRO-MP	
Viscosity	10~100Pa·s
Sintering Temperature	230°C ↑ x300sec
Sintering Pressure	20MPa ↑
Thermal Conductivity (W/m·K)	测量中
Shear Strength	30MPa
Target Metal	Ag,Au,Pd,Pt

ASTRO-LP	
Viscosity	10~100Pa·s
Sintering Temperature	220°C ↑ x300sec
Sintering Pressure	10MPa ↑
Thermal Conductivity (W/m·K)	350W/m·K
Shear Strength	20MPa
Target Metal	Ag,Au,Pd,Pt, (Cu)

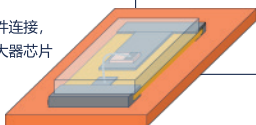
TIM 应用

适用于对导热率要求高、传统导热油膏或导热片不足以满足需求的模块

不可加压器件应用

无空洞 / 无加压连接

非常适合用于无法加压的器件连接, 如高功率放大器芯片和发光器件



ASTRO-LN	
Viscosity	10~300Pa·s
Sintering Temperature	250°C ↑ x 60min
Sintering Pressure	0MPa
Thermal Conductivity (W/m·K)	155W/m·K
Shear Strength	20MPa
Target Metal	Ag,Au,Pd,Pt

芯片粘接应用

